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May 2015

# FGA6065ADF 650 V, 60 A Field Stop Trench IGBT

#### **Features**

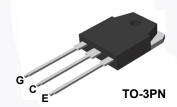
- Maximum Junction Temperature :  $T_J = 175$  °C
- · Positive Temperaure Co-efficient for Easy Parallel Operating
- · High Current Capability
- Low Saturation Voltage:  $V_{CE(sat)}$  = 1.8 V (Typ.) @  $I_C$  = 60 A
- 100% of the Parts Tested for I<sub>LM</sub> (1)
- High Input Impedance
- · Fast Switching
- · RoHS Compliant

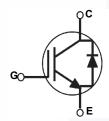
#### **General Description**

This ADF IGBT series adopted Field Stop Trench 3rd generation IGBT which offer extreme low Rds(on) and much faster switching characteristics for outstanding efficiency. And this kind of technology is fully optimized to variety PFC (Power Factor Correction) topology; Single boost, Multi channel interleaved etc with over 20KHz switching performance. TO3P package provide Super Low thermal resistance for much wider SOA for system stability.

#### **Applications**

- PFC topology for Home appliance: Single Boost, Multi channel Interleaved etc.
- · PFC Topology for Welder





## **Absolute Maximum Ratings**

Symbol	Description		FGA6065ADF	Unit
V <sub>CES</sub>	Collector to Emitter Voltage		650	V
V	Gate to Emitter Voltage		± 20	V
$V_{GES}$	Transient Gate to Emitter Voltage		± 30	V
l <sub>o</sub>	Collector Current	@ T <sub>C</sub> = 25°C	120	Α
IC	Collector Current	@ T <sub>C</sub> = 100°C	60	Α
I <sub>LM (1)</sub>	Pulsed Collector Current	@ T <sub>C</sub> = 25°C	180	Α
I <sub>CM (2)</sub>	Pulsed Collector Current		180	А
l <sub>F</sub>	Diode Forward Current	@ T <sub>C</sub> = 25°C	60	А
'F	Diode Forward Current	@ T <sub>C</sub> = 100°C	30	А
I <sub>FM (2)</sub>	Pulsed Diode Maximum Forward Curren	t	120	А
P <sub>D</sub>	Maximum Power Dissipation	@ T <sub>C</sub> = 25°C	306	W
ı D	Maximum Power Dissipation	@ T <sub>C</sub> = 100°C	153	W
TJ	Operating Junction Temperature		-55 to +175	°C
T <sub>stg</sub>	Storage Temperature Range		-55 to +175	°C
T <sub>L</sub>	Maximum Lead Temp. for soldering Purposes, 1/8" from case for 5 seconds		300	°C

#### Notes

- 1.  $\rm V_{CC}$  = 400 V,  $\rm V_{GE}$  = 15 V,  $\rm I_{C}$  =180 A,  $\rm R_{G}$  = 48.4  $\Omega,$  Inductive Load
- 2. Repetitive rating: Pulse width limited by max. junction temperature

### **Thermal Characteristics**

Symbol	Parameter	FGA6065ADF	Unit	
$R_{\theta JC}(IGBT)$	Thermal Resistance, Junction to Case, Max.	0.49	°C/W	
$R_{\theta JC}(Diode)$	Thermal Resistance, Junction to Case, Max.	1.75	°C/W	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max.	40	°C/W	

# **Package Marking and Ordering Information**

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FGA6065ADF	FGA6065ADF	TO-3PN	Tube	-	-	30

## Electrical Characteristics of the IGBT T<sub>C</sub> = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Off Charac	eteristics					
BV <sub>CES</sub>	Collector to Emitter Breakdown Voltage	$V_{GE}$ = 0V, $I_C$ = 1 mA	650	-	-	V
ΔBV <sub>CES</sub> / ΔΤ <sub>J</sub>	Temperature Coefficient of Breakdown Voltage	I <sub>C</sub> = 1 mA, Reference to 25°C	-	0.6	-	V/°C
I <sub>CES</sub>	Collector Cut-Off Current	$V_{CE} = V_{CES}, V_{GE} = 0 V$	-	-	250	μА
I <sub>GES</sub>	G-E Leakage Current	V <sub>GE</sub> = V <sub>GES</sub> , V <sub>CE</sub> = 0 V	-	-	±400	nA
On Charac	teristics					
V <sub>GE(th)</sub>	G-E Threshold Voltage	$I_C$ = 60 mA, $V_{CE}$ = $V_{GE}$	4.1	5.6	7.6	V
()		I <sub>C</sub> = 60 A, V <sub>GE</sub> = 15 V	-	1.8	2.3	V
V <sub>CE(sat)</sub>	Collector to Emitter Saturation Voltage	I <sub>C</sub> = 60 A, V <sub>GE</sub> = 15 V, T <sub>C</sub> = 175°C	-	2.3	-	٧
Dynamic C	Characteristics					
C <sub>ies</sub>	Input Capacitance		-	2419	-	pF
C <sub>oes</sub>	Output Capacitance	$V_{CE} = 30 \text{ V}, V_{GE} = 0 \text{ V},$ f = 1MHz	-	82	-	pF
C <sub>res</sub>	Reverse Transfer Capacitance	11 - 1101112	-	31	-	pF
Switching	Characteristics					
t <sub>d(on)</sub>	Turn-On Delay Time		-	25.6	-	ns
t <sub>r</sub>	Rise Time		_	67.2	- /	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$V_{CC} = 400 \text{ V}, I_{C} = 60 \text{ A},$	-	71	-	ns
t <sub>f</sub>	Fall Time	$R_G = 6 \Omega$ , $V_{GE} = 15 V$ ,	-	22	-	ns
E <sub>on</sub>	Turn-On Switching Loss	Inductive Load, T <sub>C</sub> = 25°C	-	2.46	// <b>-</b>	mJ
E <sub>off</sub>	Turn-Off Switching Loss		-	0.52	- //	mJ
E <sub>ts</sub>	Total Switching Loss		-	2.98	-	mJ
t <sub>d(on)</sub>	Turn-On Delay Time		-	22.4	- \	ns
t <sub>r</sub>	Rise Time		_	63.2	-	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$V_{CC} = 400 \text{ V}, I_{C} = 60 \text{ A},$	-	77	-	ns
t <sub>f</sub>	Fall Time	$R_G = 6 \Omega$ , $V_{GE} = 15 V$ ,	-	22	-	ns
E <sub>on</sub>	Turn-On Switching Loss	Inductive Load, T <sub>C</sub> = 175°C	-	3.19	-	mJ
E <sub>off</sub>	Turn-Off Switching Loss		-	0.71	-	mJ
E <sub>ts</sub>	Total Switching Loss	]	-	3.90	-	mJ

# Electrical Characteristics of the IGBT (Continued)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max	Unit
$Q_g$	Total Gate Charge	V <sub>CE</sub> = 400 V, I <sub>C</sub> = 60 A, V <sub>GE</sub> = 15 V	-	84	-	nC
Q <sub>ge</sub>	Gate to Emitter Charge		-	15	-	nC
Q <sub>gc</sub>	Gate to Collector Charge		-	32	-	nC

## Electrical Characteristics of the Diode $T_C = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter		Test Conditions		Min.	Тур.	Max	Unit	
V <sub>FM</sub>	Diode Forward Voltage	I <sub>F</sub> =	30 A		T <sub>C</sub> = 25°C	-	1.8	2.3	V
FM				Ī	T <sub>C</sub> = 175°C	-	1.7	-	
E <sub>rec</sub>	Reverse Recovery Energy				T <sub>C</sub> = 175°C	-	233	-	uJ
t	Diode Reverse Recovery Time	$I_F = 30 \text{ A}, dI_F/dt = 200 \text{ A}/\mu\text{s}$	Ī	T <sub>C</sub> = 25°C	-	110	-	ns	
r <sub>rr</sub> Diode i	Blodd Novolod Nodovoly Time		50 A, αιρ/αι – 200 A/μS	Ī	T <sub>C</sub> = 175°C	-	271	-	110
Q <sub>rr</sub>	Diode Reverse Recovery Charge			Ī	T <sub>C</sub> = 25°C	-	400	-	nC
α <sub>II</sub>	Blodd Novolod Nodovoly Charge			Ī	T <sub>C</sub> = 175°C	-	1740	-	110

**Figure 1. Typical Output Characteristics** 

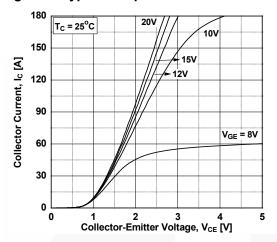


Figure 3. Typical Saturation Voltage Characteristics

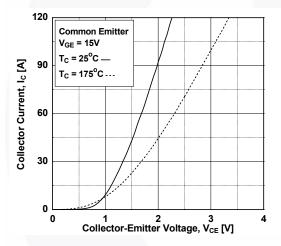
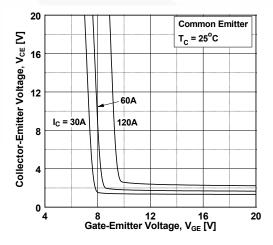


Figure 5. Saturation Voltage vs. V<sub>GE</sub>



**Figure 2. Typical Output Characteristics** 

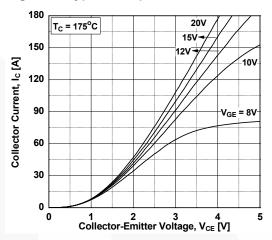


Figure 4. Saturation Voltage vs. Case
Temperature at Variant Current Level

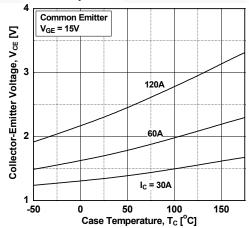


Figure 6. Saturation Voltage vs.  $V_{GE}$ 

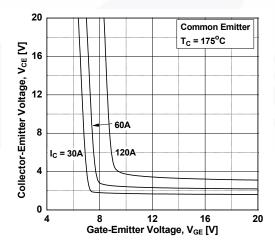


Figure 7. Capacitance Characteristics

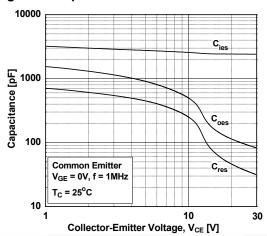


Figure 9. Turn-on Characteristics vs.
Gate Resistance

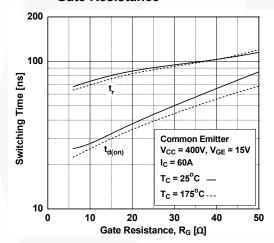


Figure 11. Switching Loss vs.
Gate Resistance

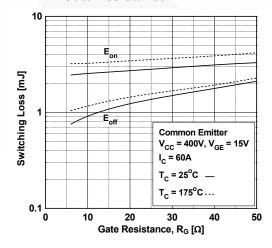


Figure 8. Gate charge Characteristics

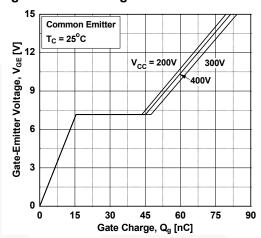


Figure 10. Turn-off Characteristics vs. Gate Resistance

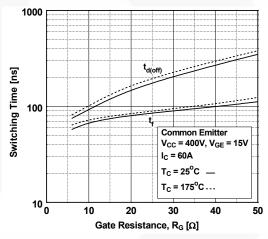


Figure 12. Turn-on Characteristics vs. Collector Current

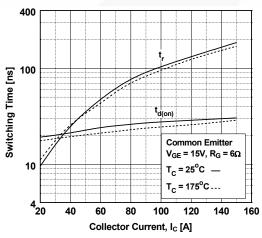


Figure 13. Turn-off Characteristics vs. Collector Current

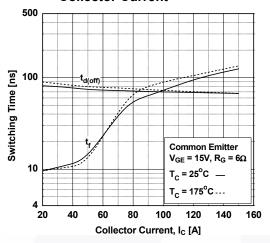


Figure 14. Switching Loss vs. Collector Current

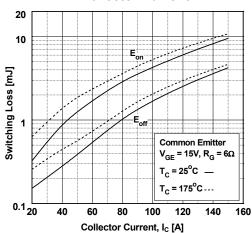


Figure 15. Load Current Vs. Frequency

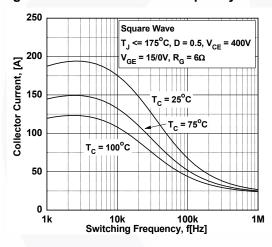


Figure 16. SOA Characteristics

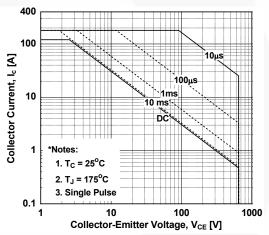


Figure 17. Forward Characteristics

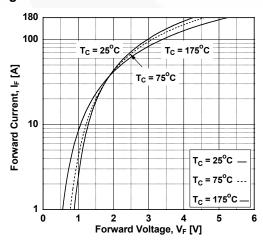


Figure 18. Reverse Recovery Current

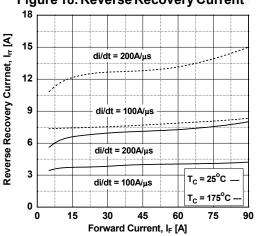


Figure 19. Reverse Recovery Time

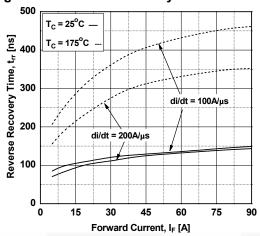


Figure 20. Stored Charge

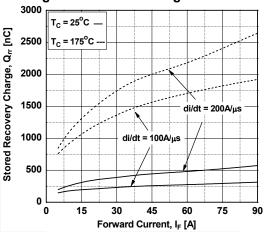


Figure 21.Transient Thermal Impedance of IGBT

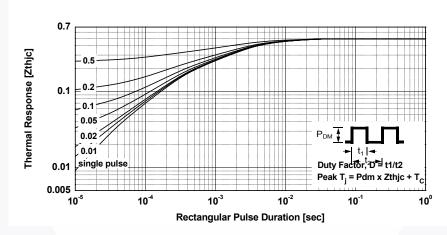
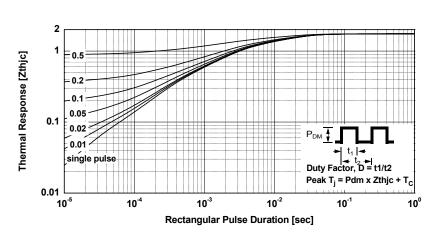
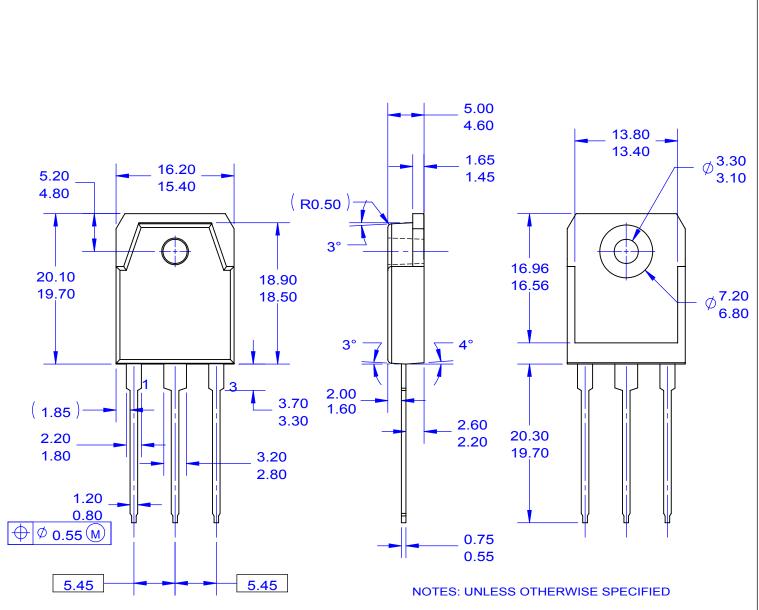
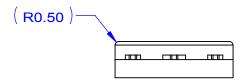


Figure 22. Transient Thermal Impedance of Diode







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- B) ALL DIMENSIONS ARE IN MILLIMETERS.
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